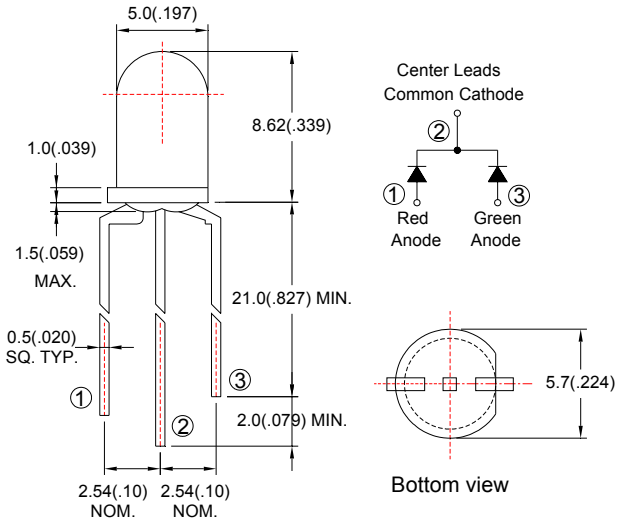
● Features:

1. Chip material: AlGaInP/GaAs (Red)
   and AlGaInP/GaAs (Green)
2. Emitted color : Red and Green
3. Lens Appearance : White Diffused
4. Low power consumption.
5. High efficiency.
6. Versatile mounting on P.C. Board or panel.
7. Low current requirement.
8. 5mm diameter package.
9. This product don't contained restriction substance, compliance RoHS standard.

● Applications:

1. TV set
2. Monitor
3. Telephone
4. Computer
5. Circuit board

● Package dimensions



Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is ±0.25mm (0.01") unless otherwise specified.
3. Lead spacing is measured where the leads emerge from the package.
4. Specifications are subject to change without notice.

● Absolute Maximum Ratings(Ta=25℃)

Parameter	Symbol	Red	Green	Unit
Power Dissipation	Pd	80	80	mW
Forward Current	I_F	30	30	mA
Peak Forward Current	I_{FP}	150	150	mA
Reverse Voltage	V_R	5		V
Operating Temperature	Topr	-40℃~85℃		
Storage Temperature	Tstg	-40℃~100℃		
Soldering Temperature	Tsol	260℃max (for 5 seconds)		
Hand Soldering Temperature	Tsol	350℃max(for 3 seconds)		

*[1]Condition for I_{FP} is pulse of 1/10 duty and 0.1msec width.

● Electrical and optical characteristics(Ta=25℃)

Parameter	Symbol	Condition	Color	Min.	Typ.	Max.	Unit
Forward Voltage	V_F	I_F=20mA	Red Green	-	2.0 2.0	2.6 2.6	V
Luminous Intensity	Iv	I_F=20mA	Red Green	-	320 130	-	mcd
Reverse Current	I_R	V_R=5V	Red Green	-	-	100	μA
Peak Wave Length	λp	I_F=20mA	Red Green	-	645 570	-	nm
Dominant Wave Length	λd	I_F=20mA	Red Green	627 565	-	637 576	nm
Spectral Line Half-width	Δλ	I_F=20mA	Red Green	-	22 30	-	nm
Viewing Angle	$2\theta_{1/2}$	I_F=20mA	Red Green	-	50	-	deg

● Typical Electro-Optical Characteristics Curves

Fig.1 Relative intensity vs. Wavelength

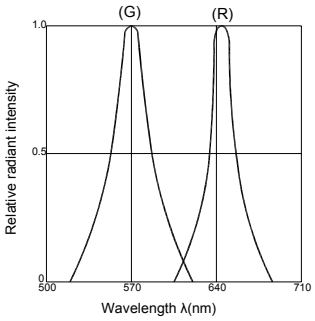


Fig.2 FORWARD CURRENT DERATING CURVE

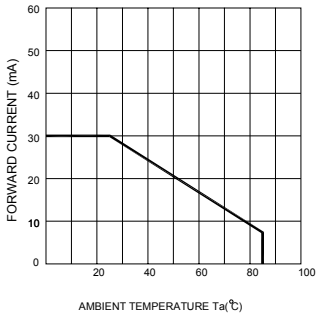


Fig.3 FORWARD CURRENT VS. FORWARD VOLTAGE

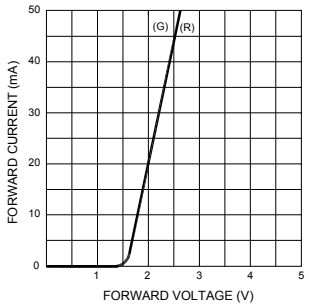


Fig.4 RELATIVE LUMINOUS INTENSITY VS. AMBIENT TEMPERATURE

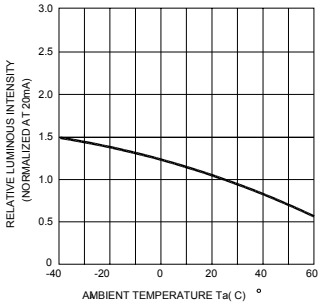


Fig.5 RELATIVE LUMINOUS INTENSITY VS. FORWARD CURRENT

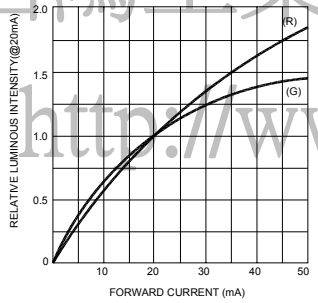
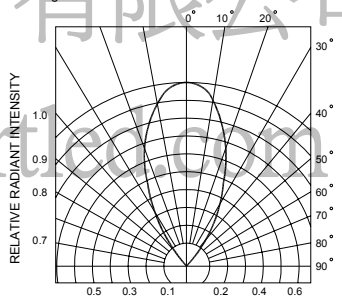


Fig.6 RADIATION DIAGRAM



●DIP soldering (Wave Soldering)

Preheating : 120℃,within 120~180 sec.
Operation heating : 255℃±5℃ within 5 sec.260℃ (Max)
Gradual Cooling (Avoid quenching).